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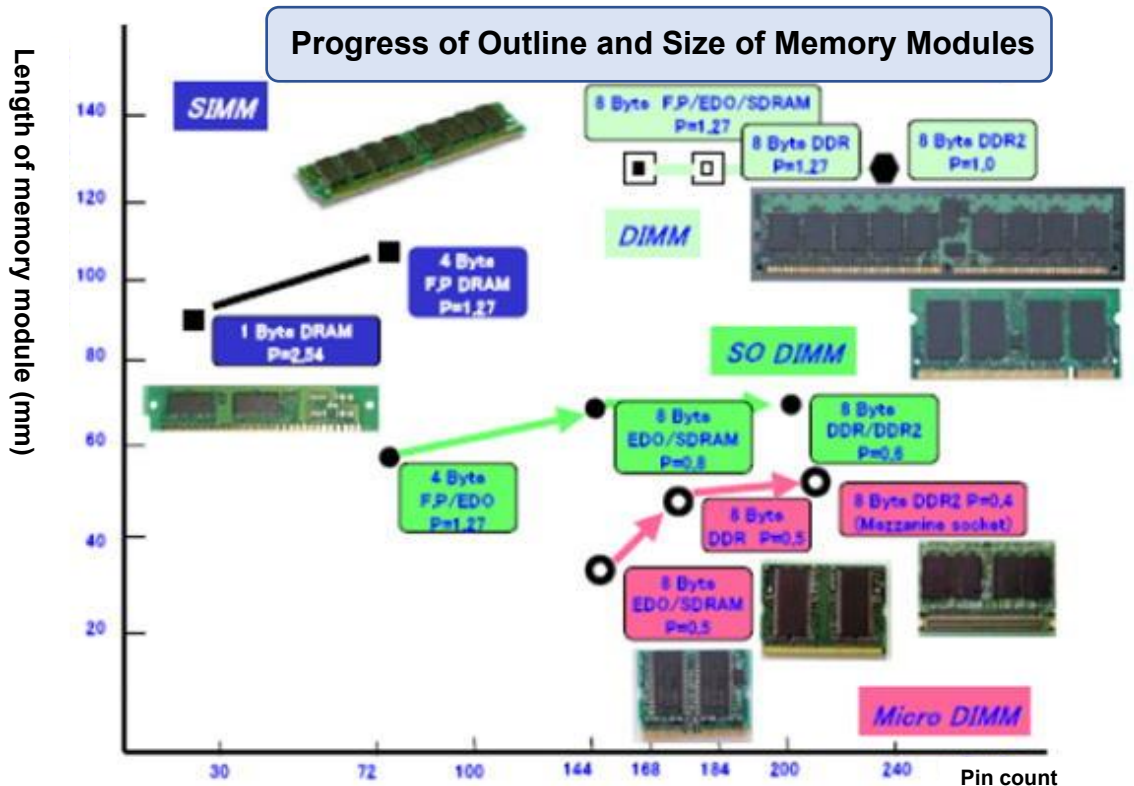
Release of DRAM memory modules using TSV

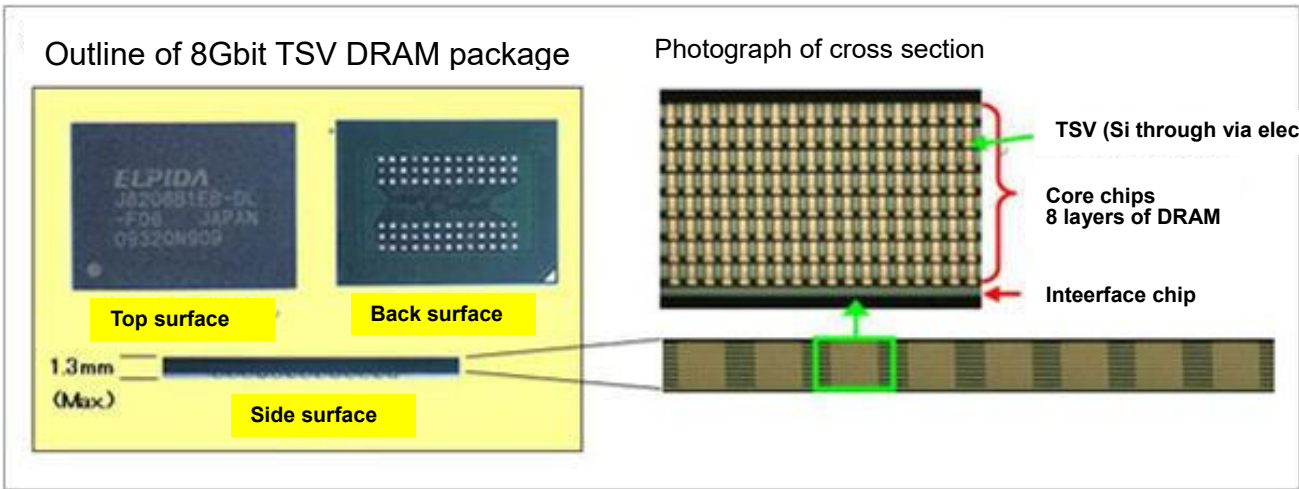
~ Packaging ~

Until the latter half of 1980s, DRAM memory modules were made by solder connection of multiple memory components to printed circuit substrates. Then, at the beginning of 1990, DIMM (Dual In-line Memory Module) was established as an assembling method for PC and server application, in which 8 to 9 packaged memory components were assembled on a small printed substrate, which then was inserted to the sockets installed on the mother board.

SODIMM (Small Outline DIMM) was developed mainly by Elpida Memory for the application to notebook PCs, and it further evolved to MicroDIMM to cope with the advent of netbooks and internet connection type mobile phones around 2005.

DRAM memory has been integrated into the function of a memory module, and then the memory capacity is continuously increasing. In August 2009 Elpida Memory announced that higher density DRAM memory modules would be realized by use of multi-stacking technology such as TSV with the completion of the development.





Version 2019/1/31